



## PROGRAM AT GLANCE

	EXHIBITION & CATERING Alexander I + II and Foyer	SESSION 1 Grenander I + II	SESSION 2 Grenander III + IV	SIDE EVENTS & POSTER SESSION Alexander III
<b>Monday, 26.9.</b>				
09.30–11.00		<b>Tutorial</b> Introduction to the Modern Reliability Based on Physics and Statistics	<b>Tutorial</b> Model-based Hierarchical Reliability Analysis	
11.00–11.30			Coffee Break	
11.30–13.00			<b>Tutorial</b> Influence of Cosmic Radiation on Power Semiconductor Reliability	
13.00–14.30	Exhibitors Booth Setup Starting from 13.00	Room Conversion		
14.30–17.30		<b>Opening</b> Welcome by Conference Chair, Keynotes, Invited Talk 1		
17.30–19.30	<b>Exhibition Opening &amp; Get Together</b>			
<b>Tuesday, 27.9.</b>				
08.30–09.00	Exhibition	<b>Invited Talk 2</b> Nanoscale Conductivity Mapping: Live Imaging of Dielectric Breakdown with STEM EBIC		
09.00–10.40		<b>A1</b> Mission Profiles, Modeling and Testing	<b>F1</b> Smart Power Devices, IGBT and MOSFETS	<b>Veletektronik Workshop</b> Session I – Hardware Security
10.40–11.20	<b>Coffee Break &amp; Exhibition</b>		<b>Poster Exhibition</b>	
11.20–13.00	Exhibition	<b>A2</b> Reliability Assessment of Complex Systems and Underlying Technologies	<b>D</b> Microwave Devices and Circuits <b>Invited Talk 3</b> Reliability Challenges on GaN Technology Designed for Highly Linear Sub 6GHz Applications	<b>Veletektronik Workshop</b> Session II – Counterfeit Detection
13.00–14.00		<b>Lunch Break &amp; Exhibition</b>		<b>Poster Exhibition</b>
14.00–15.40	Exhibition	<b>E1</b> Wafer- and Panel-Level Interconnection Technologies	<b>F2</b> SiC Device Reliability	<b>Veletektronik Workshop</b> Session III – PUFs
15.40–16.20		<b>Coffee Break &amp; Exhibition</b>		<b>Poster Exhibition</b>
16.20–18.00	Exhibition	<b>E1 &amp; E2</b> Interconnects	<b>F2</b> GaN Device Reliability	<b>Veletektronik Workshop</b> Session IV – IC Trojan Detection
<b>Wednesday, 28.9.</b>				
08.30–09.00	Exhibition	<b>Invited Talk 4</b> Vector Magnetic Current Imaging of an 8 nm Process Node Chip and 3D Current Distributions Using the Quantum Diamond Microscope		
09.00–10.40		<b>B</b> Modern Memory Technologies and Thermomigration Modelling	<b>F3</b> Power Electronic Systems 1	<b>APPLAUSE Session 1</b> Introduction to Applause
10.40–11.20	<b>Coffee Break &amp; Exhibition</b>		<b>Poster Exhibition</b>	
11.20–13.00	Exhibition	<b>B</b> Aging in Device Technologies	<b>F3</b> Power Electronic Systems 2	<b>APPLAUSE Session 2</b> Hermetic Wafer Level Bonding for MEMS/MOEMS Applications
13.00–14.00		<b>Lunch Break &amp; Exhibition</b>		<b>Poster Exhibition</b>
14.00–15.40	Exhibition	<b>C</b> Progress in Failure Analysis Methods	<b>E2</b> Second-Level Interconnects	<b>APPLAUSE Session 3</b> High-speed Datacom 400Gb/s Transceiver with Reduced Manufacturing Cost
15.40–16.00		<b>Coffee Break &amp; Exhibition</b>		<b>Poster Exhibition</b>
16.00–17.30				<b>Interactive Poster Session</b> with Poster Presenters
19.00–23.00	<b>Conference Dinner at Wasserwerk</b> <small>Bus transfers start from 18.10 in front of the H4 Hotel</small>			
<b>Thursday, 29.9.</b>				
09.00–10.40	Exhibition	<b>H</b> MEMS and Sensors	<b>I</b> Extreme Environments and Radiation I	<b>APPLAUSE</b> Summer School
10.40–11.20		<b>Coffee Break &amp; Exhibition</b>		<b>Poster Exhibition</b>
11.20–13.00	Exhibition	<b>G</b> Reliability of Light Emitters and Solar Cells	<b>I</b> Extreme Environments and Radiation II	<b>APPLAUSE</b> Summer School
13.00–14.00		<b>Lunch Break &amp; Exhibition</b>		<b>Poster Exhibition</b>
14.00–15.30		<b>Closing Ceremony</b>		<b>APPLAUSE</b> Summer School

### Conference Tracks

**A** – Assessment Techniques and Methods for Devices and Systems  
**B** – Semiconductor and Nanoelectronics Technologies  
**C** – Progress in Failure Analysis Methods

**D** – Microwave Devices and Circuits  
**E** – Packaging and Assemblies  
**F** – Power Devices and Systems

**G** – Photonics Devices  
**H** – MEMS and Sensors  
**I** – Extreme Environments and Radiation